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(54) Title: HEAD SUSPENSION WITH FLEXIBLE CIRCUIT INTERCONNECT FOR REDUCED MOISTURE PERMEABILITY

(57) Abstract

The invention provides a disk drive suspension including a transducer head electrically connected to a suspension by means of a flexible circuit having a dielectric layer and at least one layer of conductive material wherein at least one layer of diamon like carbon on at least one major surface of at least one layer of the circuit, where the diamong like carbon coating has a thickness of between 300 Angstroms and 3000 Angstroms, and a hardness of from 8 to 9. The layer of diamond like carbon may be coated directly onto the dielectric material substrate, may be covercoat or may bu used in both ways.

